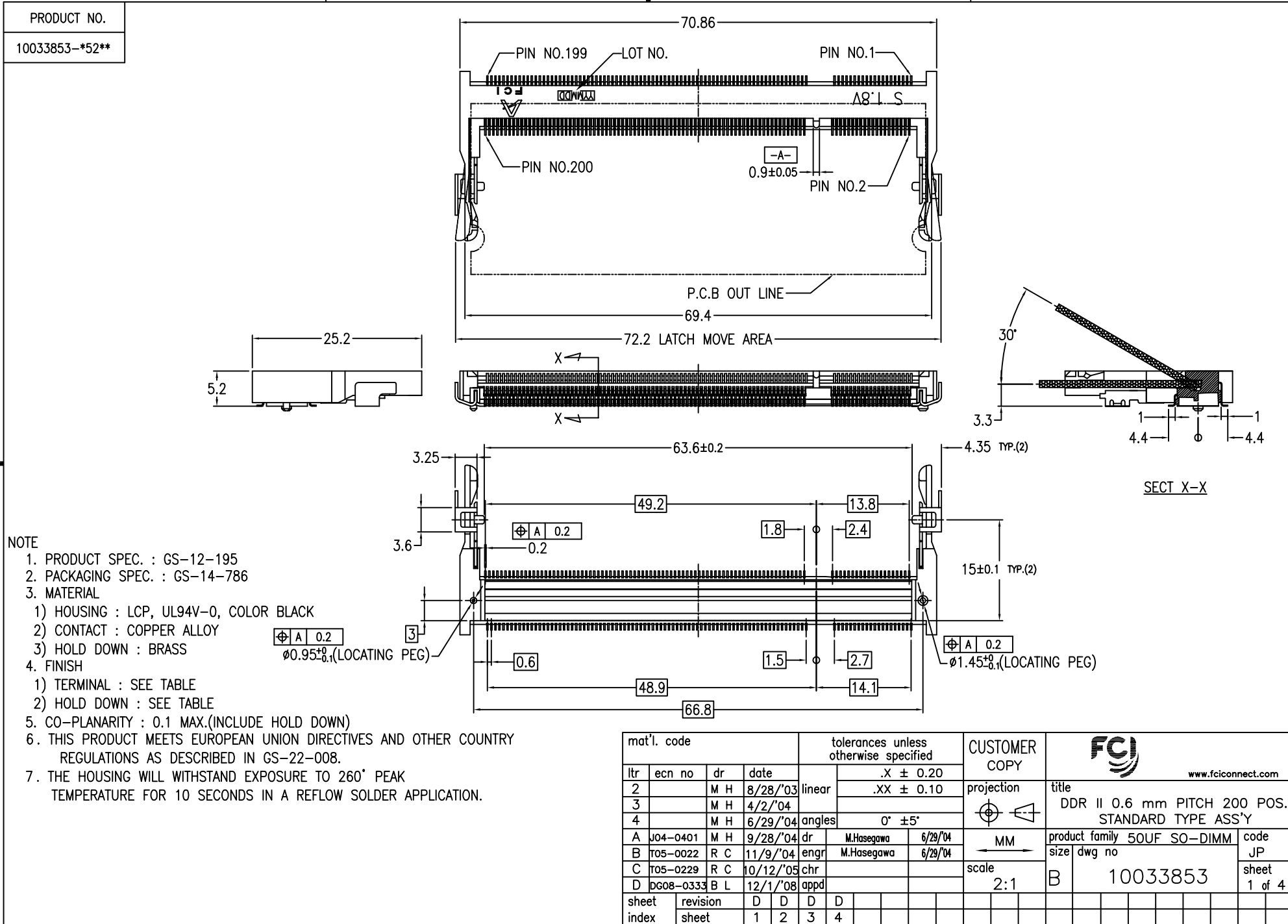
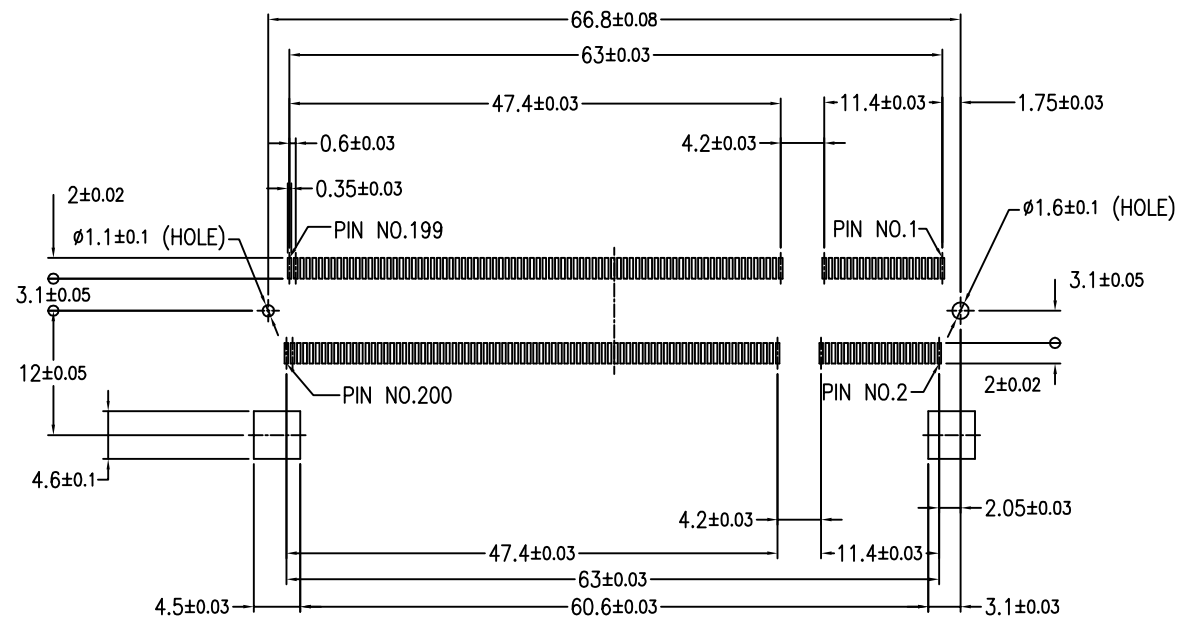




10033853-*52**

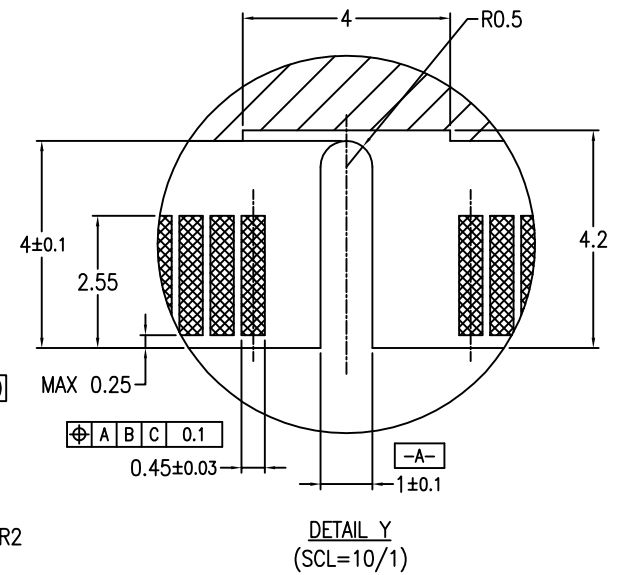
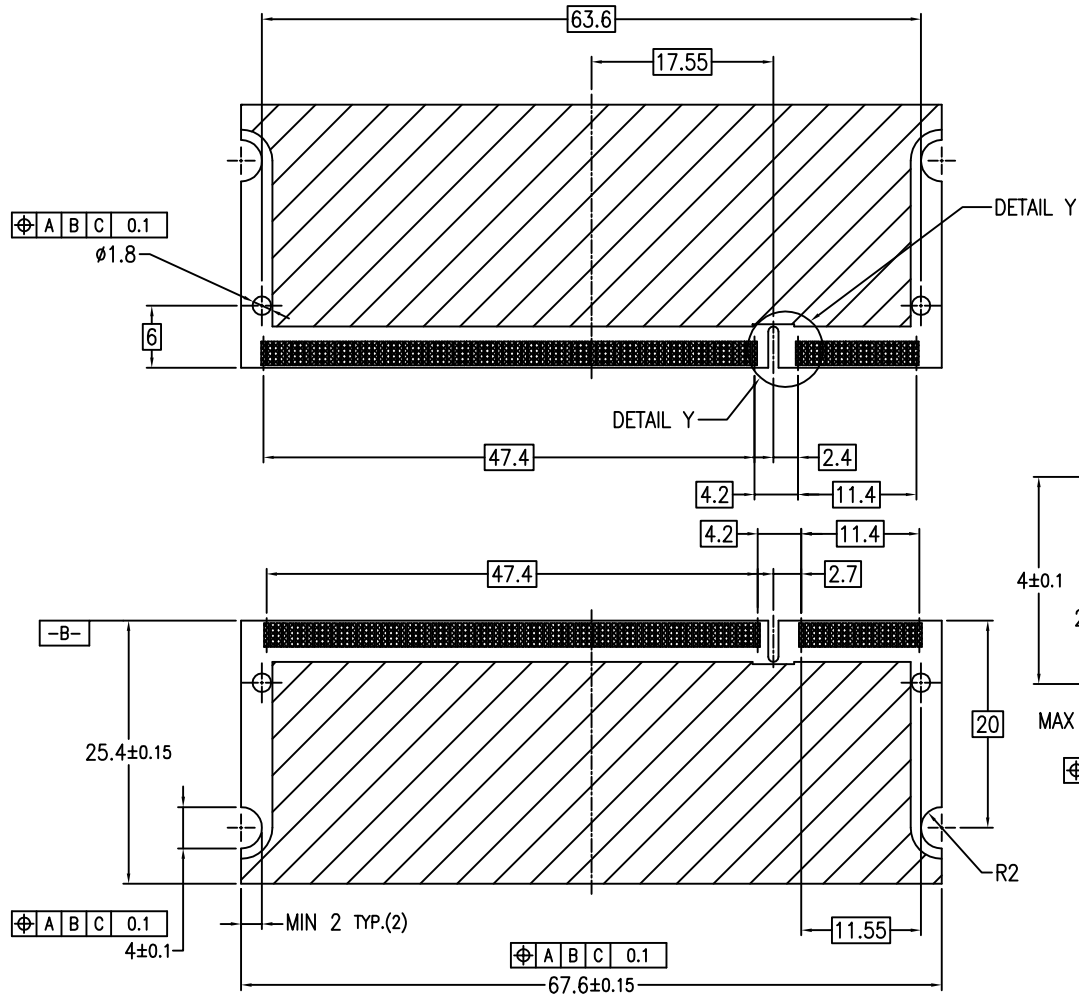
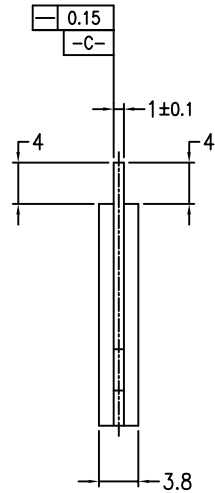


RECOMMENDED MOUNTING P.C.B LAYOUT

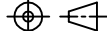
[illegible]



PRODUCT NO.
10033853-*52**



RECOMMENDED MODULE P.C.B. LAYOUT

mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		 www.fciconnect.com								
ltr	ecn no	dr	date	linear	.X ± 0.20				projection 	title DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASS'Y								
D					.XX ± 0.10													
					angles	0° ±5°												
				dr		M.Hasegawa	6/29/04	MM 	product family 50UF SO-DIMM				code					
				engr	M.Hasegawa	6/29/04	scale 2:1		size dwg no				JP					
				chr				B	10033853				sheet					
				appd									3 of					
sheet index	revision sheet																	

PRODUCT NO.	LOCATING PEG	TERMINAL CONTACT AREA FINISH	HOLD DOWN FINISH	SOLDER TAIL FINISH
10033853-052FSLF	YES	Au FLASH	PURE Sn PLATING	Au FLASH
10033853-152FSLF	NO			
10033853-052TSLF	YES	Au 0.3um MIN.		
10033853-152TSLF	NO			
10033853-052ASLF	YES	Au 0.76um MIN.		
10033853-152ASLF	NO			
10033853-052FB	YES	Au FLASH	Sn-Pb PLATING	
10033853-152FB	NO			
10033853-052TB	YES	Au 0.3um MIN.		
10033853-152TB	NO			
10033853-052AB	YES	Au 0.76um MIN.		
10033853-152AB	NO			
10033853-252FSLF	YES	Au FLASH	PURE Sn PLATING	Pure Sn PLATING
10033853-352FSLF	NO			
10033853-252TSLF	YES	Au 0.3um MIN.		
10033853-352TSLF	NO			
10033853-252ASLF	YES	Au 0.76um MIN.		
10033853-352ASLF	NO			
10033853-252FB	YES	Au FLASH	Sn-Pb PLATING	
10033853-352FB	NO			
10033853-252TB	YES	Au 0.3um MIN.		
10033853-352TB	NO			
10033853-252AB	YES	Au 0.76um MIN.		
10033853-352AB	NO			
10033853-452FS	YES	Au FLASH	PURE Sn PLATING	Sn-Pb PLATING
10033853-552FS	NO			
10033853-452TS	YES	Au 0.3um MIN.		
10033853-552TS	NO			
10033853-452AS	YES	Au 0.76um MIN.		
10033853-552AS	NO			
10033853-452FB	YES	Au FLASH	Sn-Pb PLATING	
10033853-552FB	NO			
10033853-452TB	YES	Au 0.3um MIN.		
10033853-552TB	NO			
10033853-452AB	YES	Au 0.76um MIN.		
10033853-552AB	NO			

10033853-□□□□□LF

<PACKING METHOD>

R : TAPE REEL
DEFAULT : TRAY

<HOLD DOWN FINISH>

S : Pure Sn
B : Sn-Pb

<CONTACT AREA FINISH>

F : Au FLASH
T : Au 0.3um MIN.
A : Au 0.76um MIN.

<TOTAL HEIGHT>

52 : 5.2mm

<LOCATING PEG, SOLDER TAIL FINISH>

0 : YES, Au FLASH
1 : NO, Au FLASH
2 : YES, Pure Sn PLATING
3 : NO, Pure Sn PLATING
4 : YES, Sn-Pb PLATING
5 : NO, Sn-Pb PLATINGFor Rohs OPTIONS:
TAIL PLATING CODE MUST BE 0~3.
HOLD DOWN PLATING CODE MUST BE "S".
"LF" CODE IS EXIST IN THE END.
EX: 10033853-252TSLFFOR NOT Rohs COMPATIBLE:
THIS "LF" CODE IS "BLANK".
EX:10033853-452TS

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X ± 0.20	projection 	title DDR II 0.6 mm PITCH 200 POS. STANDARD TYPE ASS'Y			
D					.XX ± 0.10					
				angles	0° ±5°	MM 	product family 50UF SO-DIMM code JP			
				dr	M.Hasegawa 6/29/04					
				enr	M.Hasegawa 6/29/04	scale 2:1	size dwg no B 10033853 sheet 4 of			
				chr						
				appd						
sheet index	revision sheet									